

**1-Line, Uni-directional, Low Capacitance  
Transient Voltage Suppressors**

**Descriptions**

The ESD5341N is a low capacitance TVS (Transient Voltage Suppressor) designed to protect high speed data interfaces. It has been specifically designed to protect sensitive electronic components which are connected to data and transmission lines from over-stress caused by ESD (Electrostatic Discharge).

The ESD5341N incorporates one pair of low capacitance steering diodes plus a TVS diode.

The ESD5341N may be used to provide ESD protection up to ±20kV (contact discharge) according to IEC61000-4-2, and withstand peak pulse current up to 4A (8/20µs) according to IEC61000-4-5.

The ESD5341N is available in DFN1006-2L package. Standard products are Pb-free and Halogen-free.

**Features**

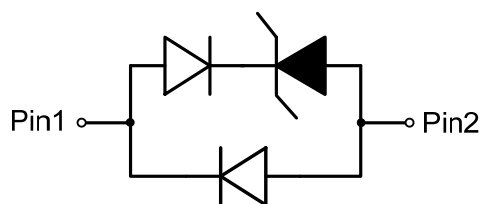
- Stand-off voltage: 5V max.
- Transient protection for each line according to  
IEC61000-4-2 (ESD): ±20kV (contact discharge)  
IEC61000-4-4 (EFT): 40A (5/50ns)  
IEC61000-4-5 (surge): 4A (8/20µs)
- Low capacitance:  $C_J = 1.0\text{pF typ.}$
- Ultra-low leakage current:  $I_R < 1\text{nA typ.}$
- Low clamping voltage:  $V_{CL} = 18\text{V typ. @ } I_{PP} = 16\text{A (TLP)}$
- Solid-state silicon technology

**Applications**

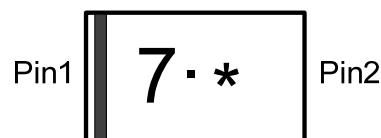
- USB Interface
- HDMI Interface
- DVI
- Portable Electronics
- Notebooks



**DFN1006-2L (Bottom View)**



**Circuit diagram**



7 = Device code  
\* = Month code ( A~Z)

**Marking (Top View)**

**Order information**

Device	Package	Shipping
ESD5341N-2/TR	DFN1006-2L	10000/Tape&Reel

**Absolute maximum ratings**

Parameter	Symbol	Rating	Unit
Peak pulse power ( $t_p = 8/20\mu s$ )	$P_{pk}$	60	W
Peak pulse current ( $t_p = 8/20\mu s$ )	$I_{PP}$	4	A
ESD according to IEC61000-4-2 air discharge	$V_{ESD}$	$\pm 20$	kV
ESD according to IEC61000-4-2 contact discharge		$\pm 20$	
Operation junction temperature	$T_J$	125	$^{\circ}C$
Lead temperature	$T_L$	260	$^{\circ}C$
Storage temperature	$T_{STG}$	-55~150	$^{\circ}C$

**Electrical characteristics ( $T_A = 25^{\circ}C$ , unless otherwise noted)**

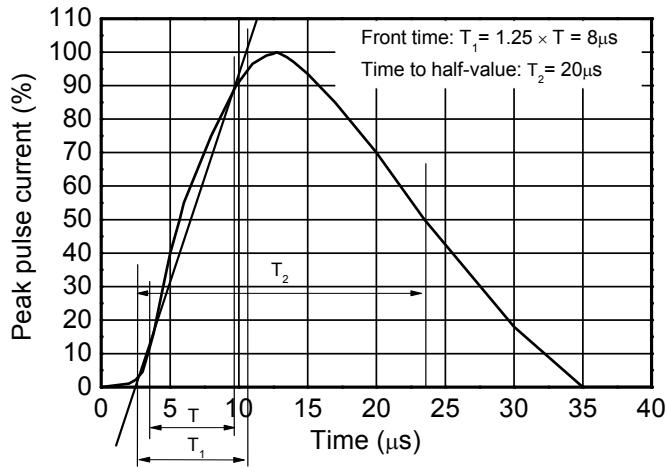
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse maximum working voltage	$V_{RWM}$				5.0	V
Reverse leakage current	$I_R$	$V_{RWM} = 5V$		<1	100	nA
Reverse breakdown voltage	$V_{BR}$	$I_T = 1mA$	7.0	8.0	9.0	V
Forward voltage	$V_F$	$I_T = 10mA$	0.6	0.9	1.2	V
Clamping voltage <sup>1)</sup>	$V_{CL}$	$I_{PP} = 16A, t_p = 100ns$		18.0		V
Dynamic resistance <sup>1)</sup>	$R_{DYN}$			0.6		$\Omega$
Clamping voltage <sup>2)</sup>	$V_{CL}$	$I_{PP} = 1A, t_p = 8/20\mu s$			11	V
		$I_{PP} = 4A, t_p = 8/20\mu s$			15	V
Junction capacitance	$C_J$	$V_R = 0V, f = 1MHz$		1.0	1.4	pF

Notes:

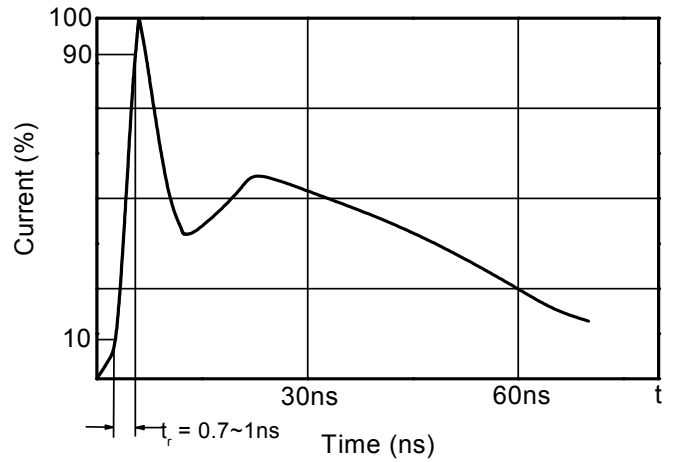
- 1) TLP parameter:  $Z_0 = 50\Omega$ ,  $t_p = 100ns$ ,  $t_r = 2ns$ , averaging window from 60ns to 80ns.  $R_{DYN}$  is calculated from 4A to 16A.
- 2) Non-repetitive current pulse, according to IEC61000-4-5.

**ESD5341N**

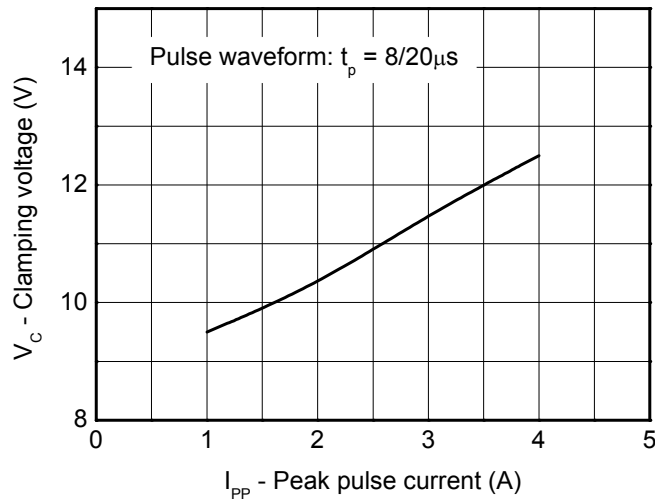
Typical characteristics ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)



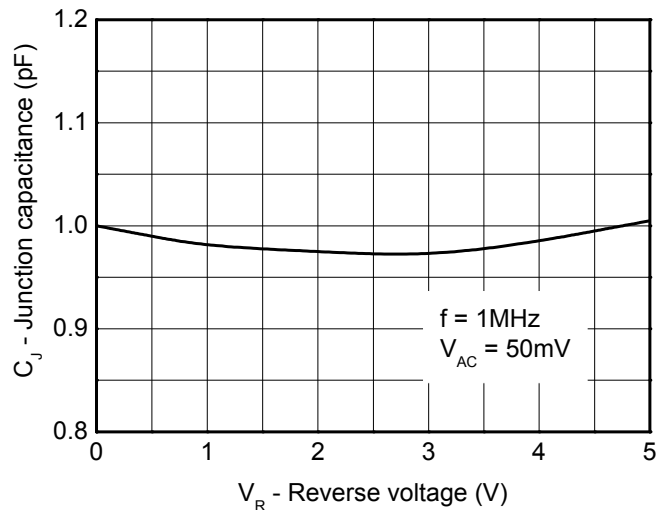
**8/20 $\mu\text{s}$  waveform per IEC61000-4-5**



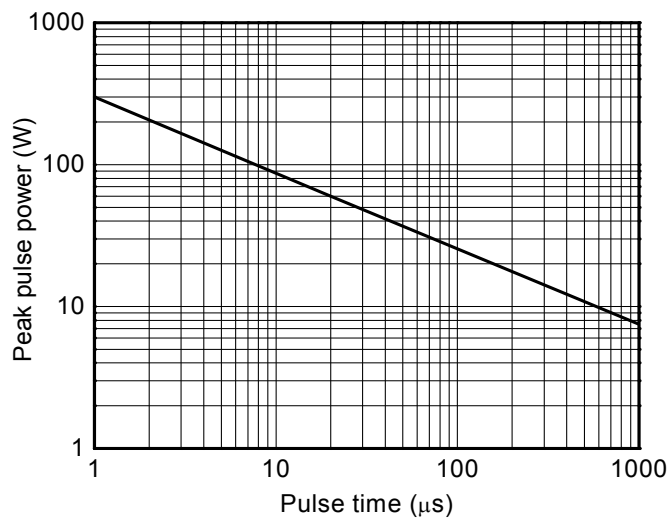
**Contact discharge current waveform per IEC61000-4-2**



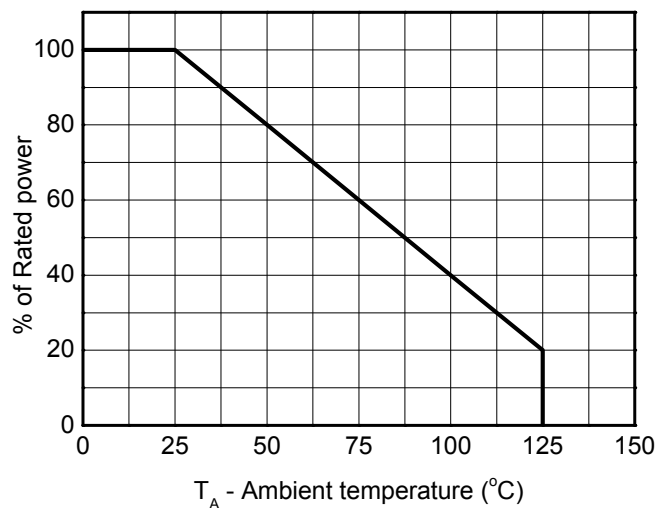
**Clamping voltage vs. Peak pulse current**



**Capacitance vs. Reverse voltage**



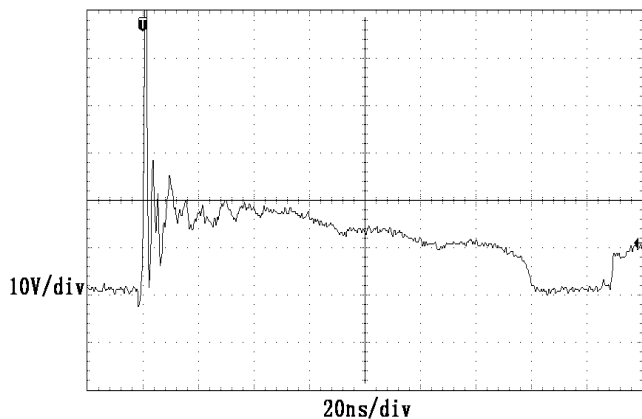
**Non-repetitive peak pulse power vs. Pulse time**



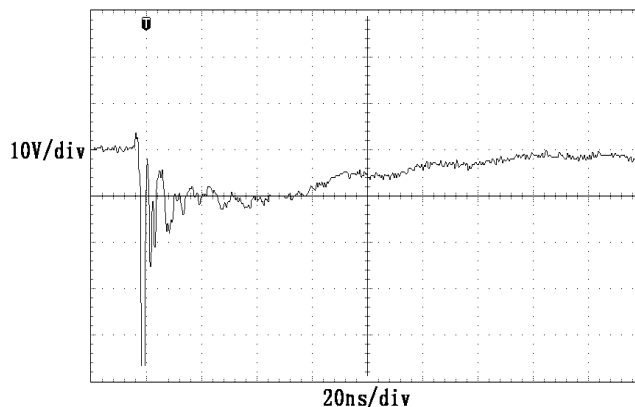
**Power derating vs. Ambient temperature**

**ESD5341N**

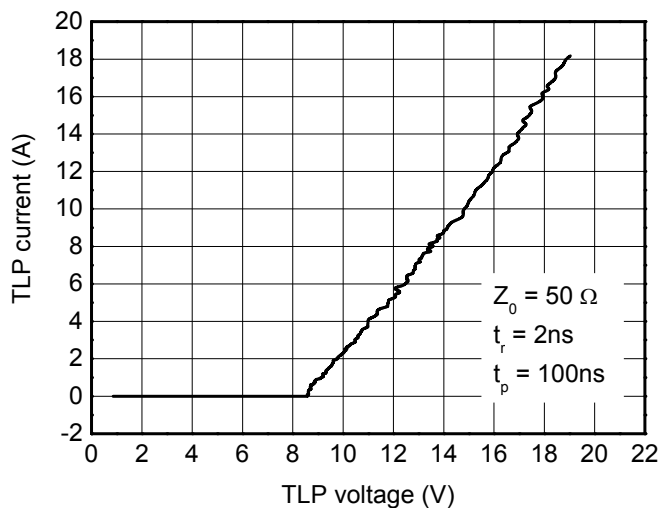
Typical characteristics ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)



**ESD clamping**  
(+8kV contact discharge per IEC61000-4-2)



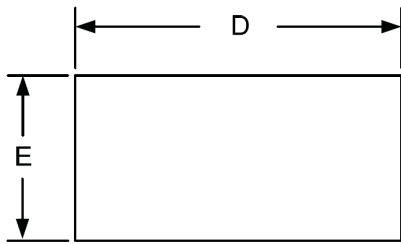
**ESD clamping**  
(-8kV contact discharge per IEC61000-4-2)



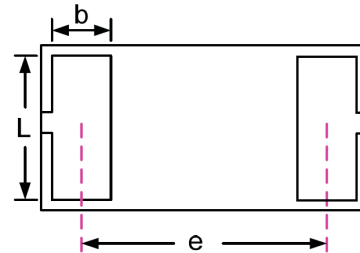
**TLP Measurement**

Package outline dimensions

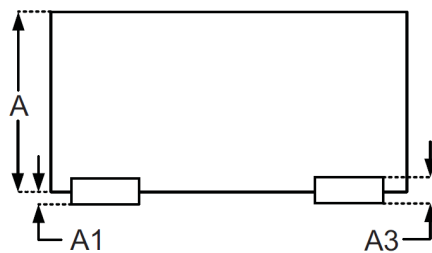
DFN1006-2L



Top View



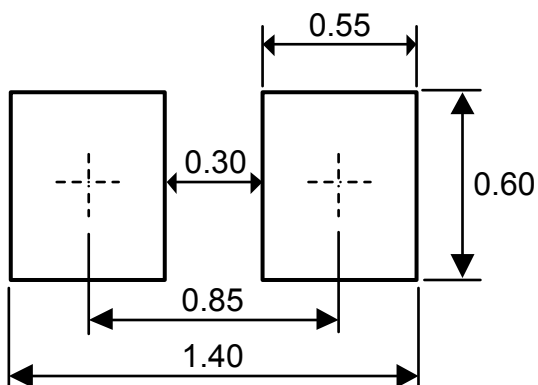
Bottom View



Side View

Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A	0.40	-	0.50
A1	0.00	-	0.05
A3	0.125 Ref.		
D	0.95	1.00	1.05
E	0.55	0.60	0.65
b	0.20	0.25	0.30
L	0.45	0.50	0.55
e	0.65 Typ.		

Recommend land pattern (Unit: mm)



Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.